

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 690121.406USPC	APPLICATION NO. 10/377538
	APPLICANTS Takayuki Shima et al.	
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	INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)	

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA					
	AB					
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FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
				YES	NO
	AF	2004-30891	JP (+ Abstract in English)		
	AG	2004-39177	JP (+ Abstract in English)		
	AH	2004-87073	JP (+ Abstract in English)		
	AI	2004-220687	JP (+ Abstract in English)		

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AJ	Extended Abstracts (The 63 rd Meeting), <i>The Japan Society of Applied Physics</i> , p. 1005, September 2002.
AK	Kikukawa, T., et al., "Rigid Bubble Pit Formation and Huge Signal Enhancement in Super-Resolution Near-Field Structure Disk with Platinum-Oxide Layer," <i>App. Phys. Lett.</i> , 81(25):4697-4699, December 16, 2002.
AL	Kim, J., et al., "Random Pattern Signal Characteristics of Super-RENS Disk at Blue Laser System," <i>Technical Digest of Optical Data Storage Topical Meeting</i> , pp. 273-275, 2004.
AM	Kim, J., et al., "Signal Characteristics of Super-RENS Disk at Blue Laser System," <i>Technical Digest of Int'l. Symposium on Optical Memory</i> , p. 263-264, 2003.
AN	Kim, J., et al., "Super-Resolution by Elliptical Bubble Formation with PtOx and AgInSbTe Layers," <i>Appl. Phys. Lett.</i> 83(9):1701-1703, September 1, 2003.
AO	Shima, T., et al., "Optical and Structural Property Change by the Thermal Decomposition of Amorphous Platinum Oxide Film," <i>Jpn. J. Appl. Phys.</i> , 42(6A):3479-3480, Part 1, June 2003.

EXAMINER /David Davis/	DATE CONSIDERED /David Davis/
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* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).